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ASSP For Power Supply Applications

Power Management 2-ch Switch IC

MB3842/MB3845

■ DESCRIPTION

The MB3842/3845 is a power management switch with built-in 2-channel low-on resistance (typ. $100m\Omega$) switch. Output control is by means of a control signal, and the MB3842 is designed for high-active operation (output on when EN is Hi), while the MB3845 is designed for low-active operation (output on when \overline{EN} is low.) To provide adaptability to a variety of operations, the MB3842/3845 features low input voltage ($V_{IN} > 2.5V$) operation and stable low-on resistance independent of input voltage. The switching current limit can be set from 100mA to 600mA by using external resistance, and when overcurrent conditions are detected the OC output goes low to provide an external notification signal.

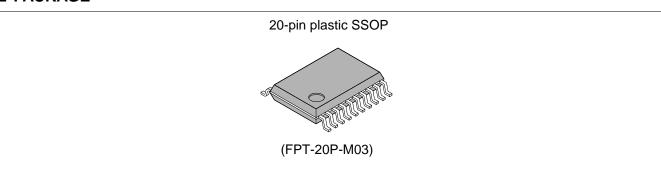
VIN is divided between the two channels, which operate independently of each other.

In addition, an off-state reverse current prevention function is provided to ensure accurate on/off switching action.

■ FEATURES

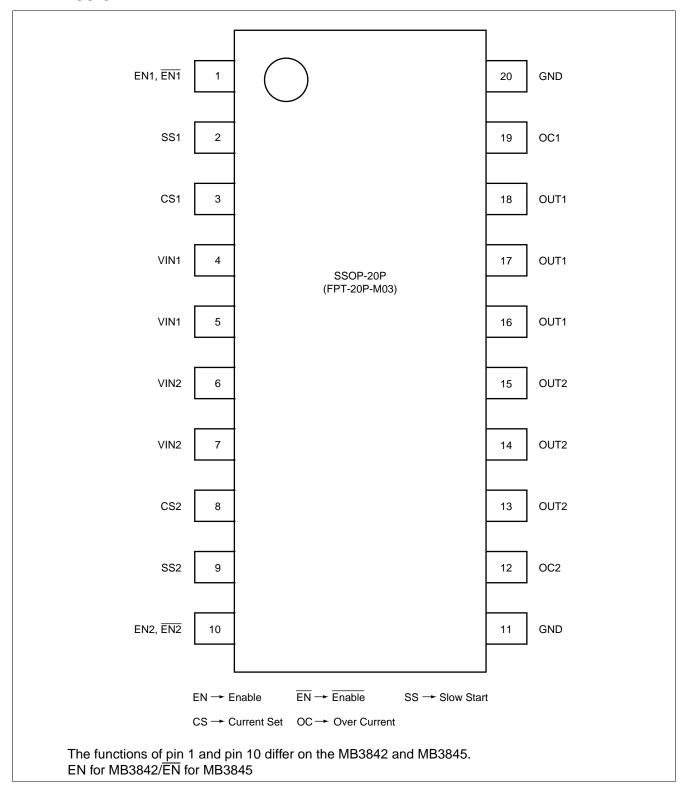
- Low on resistance switch (typ. $100m\Omega$)
- Low input voltage operation (2.5 V to 5.5 V)
- Switch current (max. 0.6 A)
- UVLO :V_{IN} threshold 2.3V/2.1 V hysteresis 200 mV
- ENABLE :EN threshold EN 1.4V/1.6 V for MB3842, EN 1/2 V_{IN} for MB3845
 - :Power supply current at output off = $0\mu A$ EN < 0.8V for MB3842, $\overline{EN} = V_{IN}$ for MB3845
- External setting for soft start time and switch current limit.
- Over-temperature detection (switch latched off), over-current detection (not latched)
- OC pin flag set following overcurrent detection, over-temperature detection, or UVLO detection.
- Reverse current prevention at OFF ($V_{IN} \ge 1.5 \text{ V}$)
- Either channel may be operated alone.

■ PACKAGE



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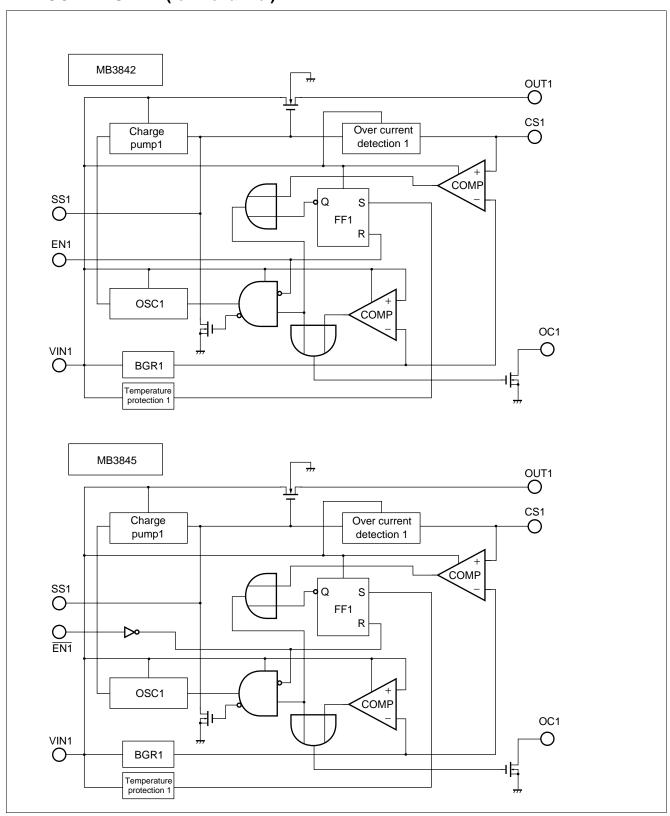
■ PIN ASSIGNMENT



■ PIN DESCRIPTION

Pin no.	Symbol	Descriptions
	EN (MB3842)	Control signal input pin. Set "H" to turn switch on, "L" to turn toff. At 0.8 V or less, the chip is in STBY state and current consumption is less than 1μ A. "L" level is 1.4V (typ), "H" level is 1.6V (typ), with 200mV (typ) hysteresis.
1/10 <u>EN</u> (MB384		Control signal input pin. Set "L" to turn switch on, "H" to turn off. At "H" level = V_{IN} , the chip is in STBY state and current consumption is less than $1\mu A$. Normally used as CMOS inverter input, so that recommended use is "L" level at GND +0.5V or less, and "H" level is V_{IN} -0.5V or greater.
2/9	SS	Slow start setting pin. Used to adjust the switch on/off timing. Add external capacitance to delay operation. Leave open when not in use. In open mode voltages up to 12 V are present. Care should be taken in mounting to prevent leakage current generation because high impedance is required.
3/8	CS	Current limit setting pin. The limit current level is set by connecting this pin to external resistance.
4/5/6/7	VIN	Switch output pin. An UVLO (VIN power monitor function) is provided so that when VIN reaches 2.3V (typ.) or higher the OC pin voltage goes to "H" level. Also if the VIN voltage drops to 2.1 V (typ.) or lower the OC output goes to "L" state. 200mV (typ) hysteresis is provided.
11/20	GND	Ground pin.
12/19	ОС	External notification pin. When the switch is in on mode this pin normally outputs a "H" level signal, but changes to "L" level when an overcurrent, overtemperature, or UVLO condition is detected. This is an open drain connection, and should be pulled up to high potential using resistance.
13/14/15 16/17/18	OUT	Switching output pin.(N-ch MOSFET source)

■ BLOCK DIAGRAM (for 1 channel)



■ ABSOLUTE MAXIMUM RATINGS

Daramatar	Symbol	Condition	Rat	Unit	
Parameter	Symbol	Condition	Max.	Min.	Offic
Input voltage	Vin	_	-0.3	7.0	V
ENABLE voltage	VEN	_	-0.3	7.0	V
Switch current	Isw	_	_	1.8	А
Power dissipation	Po	Ta = +85°C	_	216	mW
Storage temperature	Тѕтс	_	-55	+125	°C

WARNING: Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.

■ RECOMMENDED OPERATING CONDITIONS

Parameter	Cymbol	ol Condition		Unit			
Parameter	Symbol	Condition	Min.	Тур.	Max.	Oilit	
Input voltage	Vin	_	2.5	5.0	5.5	V	
ENABLE voltage	VEN	V _{EN} ≤ V _{IN}	0		5.5	V	
Switch current	Isw	V _{IN} = 2.5 V to 5.5 V	_	_	0.6	Α	
SS pin capacitance	Css*	_	_	_	10	nF	
OC sink current	locs	V _{IN} = 5.0 V, V _{OC} = 0.4 V	2.0	5.0	_	mA	
Current limit	Rlim*	V _{IN} = 5.0 V (I _{SW} = 0.6 A)	1.4	2.0	2.6	kΩ	
resistance	IXLIM	V _{IN} = 5.0 V (I _{SW} = 0.1 A)	3.6	6.2	9.1	kΩ	
Operating temperature	Тор	_	-20	_	+85	°C	

^{*:} For Css, Rlim settings, see "TYPICAL CHARACTERISTICS" and "FUNCTIONAL DESCRIPTION".

WARNING: The recommended operating conditions are required in order to ensure the normal operation of the semiconductor device. All of the device's electrical characteristics are warranted when the device is operated within these ranges.

Always use semiconductor devices within their recommended operating condition ranges. Operation outside these ranges may adversely affect reliability and could result in device failure.

No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their representatives beforehand.

■ ELECTRICAL CHARACTERISTICS (per 1 ch)

• MB3842/MB3845

Donometer	Compleal	Condition		Value			
Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit	
Switch resistance	Ron	Isw =0.6A	_	100	150	mΩ	
	I _{IN1}	Isw = 0 A	_	350	550	μΑ	
IN pin input current	I _{IN2}	Isw = 0.6 A	_	1.0	1.5	mA	
and the state of t	lına	$\frac{EN}{EN}$ < 0.8V for MB3842, \overline{EN} = V _{IN} for MB3845	_	_	1.0	μА	
UVLO threshold	Vıuн	V_{IN} at $OC = L \rightarrow H$	2.1	2.3	2.5	V	
OVLO tilleshold	VIUL	V_{IN} at $OC = H \rightarrow L$	1.9	2.1	2.3	V	
UVLO hysteresis width	VIUHY	VIUHY = VIUH — VIUL	100	200	300	mV	
Switch current limit	Iswн	$R_{\text{LIM}} = 2.0 \text{ k}\Omega$	0.42	0.6	0.78	Α	
Switch current limit	IswL	$R_{\text{LIM}} = 6.2 \text{ k}\Omega$	0.06	0.1	0.14	Α	
OC sink current	locs	Voc = 0.4 V at OC active	2.0	5.0	_	mA	
OC SINK CUITEIN	locu	Voc = 5.0 V at OC non-active	_	_	1.0	μΑ	
Temperature protection (T _i)	Тым	_	+125	_	_	°C	
OUT pin rise time ton		SS pin: Open OUT pin: 100 kΩ pull down	_	100	200	μs	
OUT pin fall time	toff	SS pin: Open OUT pin: 100 k Ω pull down	_	50	120	μs	

 $(V_{IN} = 5 \text{ V}, \text{ Ta} = +25^{\circ}\text{C})$

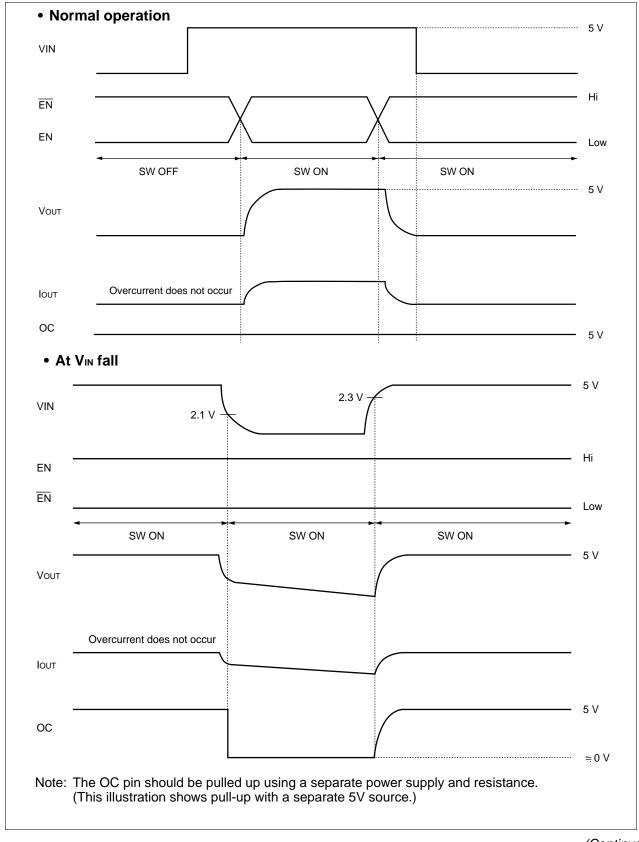
• MB3842 $(V_{IN} = 5 \text{ V}, \text{ Ta} = +25^{\circ}\text{C})$

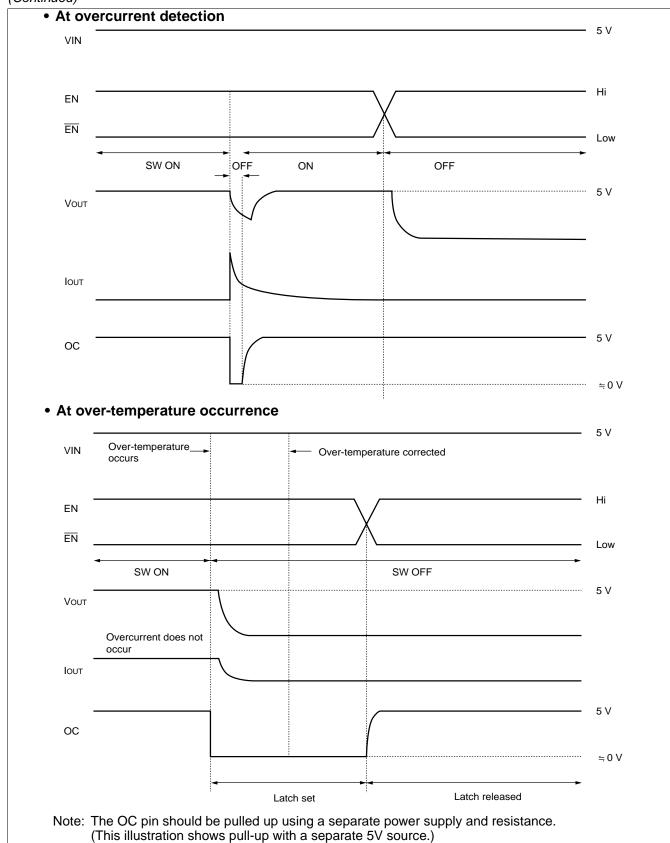
11150012		((Till 0 1) 1a . 20 0)			
Parameter	Symbol	Condition	Value			Unit
i didilietei	Symbol	Symbol		Тур.	Max.	Oilit
ENABLE pin input current	lenh	V _{EN} = 5 V, I _{SW} = 0 A	_	5	10	μΑ
LIVABLE pili iliput culletit	IENL	V _{EN} = 0 V, I _{SW} = 0 A	_	0.0		μΑ
ENABLE pin threshold	VTHEN	_	1.45	1.60	1.75	V
voltage	VTLEN		1.25	1.40	1.55	V
ENABLE hysteresis width	VENHY	VENHY = VTHEN - VTLEN	100	200	300	mV

• MB3845 $(V_{IN} = 5 \text{ V}, \text{Ta} = +25^{\circ}\text{C})$

Parameter	Symbol	Condition		Value		Unit	
raiailletei	Symbol	Condition	Min.	Тур.	Max.	Oilit	
ENABLE pin input current	lenh	V _{EN} = 5 V, I _{SW} = 0 A	_	0.0	_	μΑ	
LIVABLE piii input current	IENL	V _{EN} = 0 V, I _{SW} = 0 A	_	0.0	_	μΑ	
ENABLE pin input voltage	VILEN	_	0		8.0	V	
ENABLE piii input voitage	VIHEN	_	3.0		5.0	>	

■ DIAGRAM

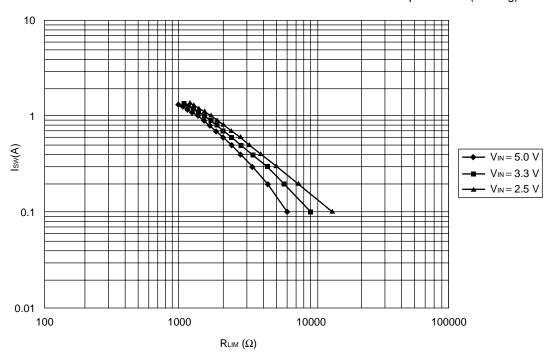




■ TYPICAL CHARACTERISTICS

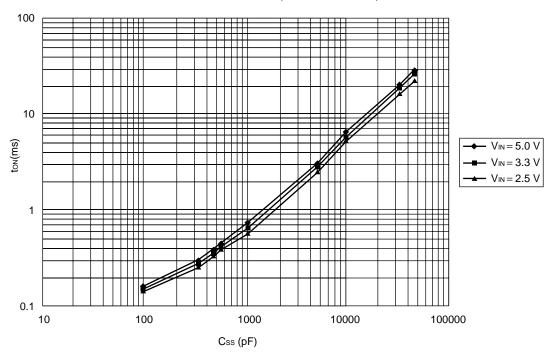
• RLIM vs. limit current characteristics

These are the limiting value characteristics for CS pin-to-GND external resistance and output current (OC flag).

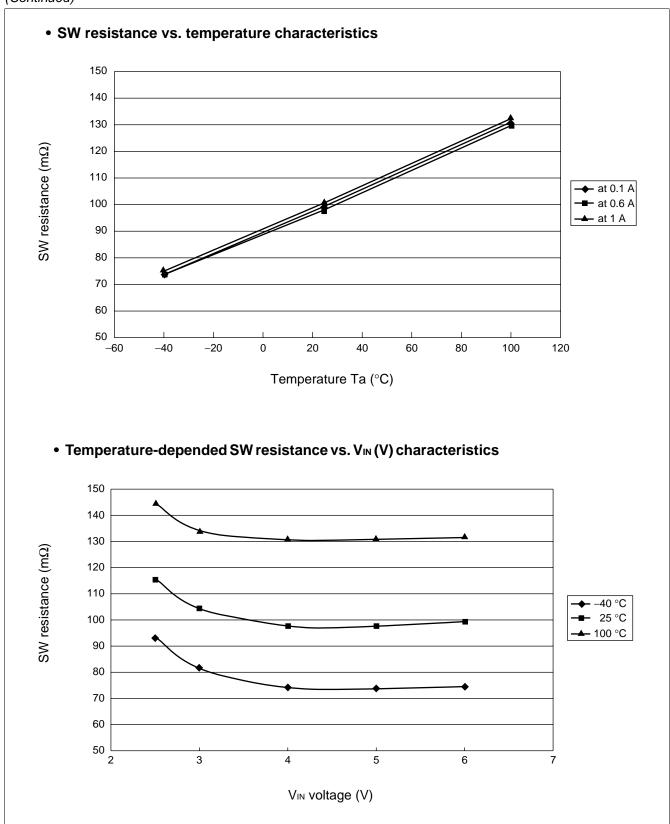


• Css vs. Ton (SS) characteristics

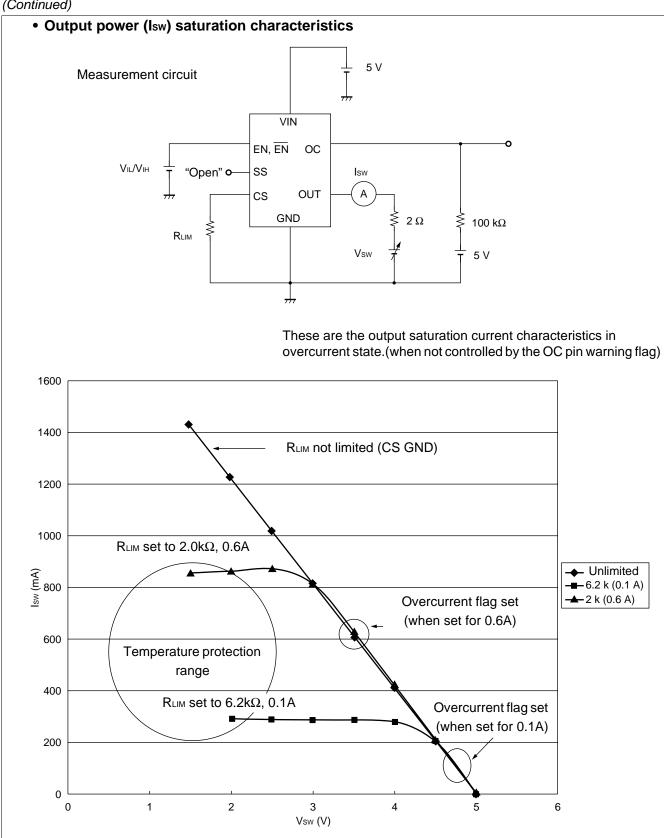
There are the characteristics for SS pin-to-GND external capacitance and output ON time.

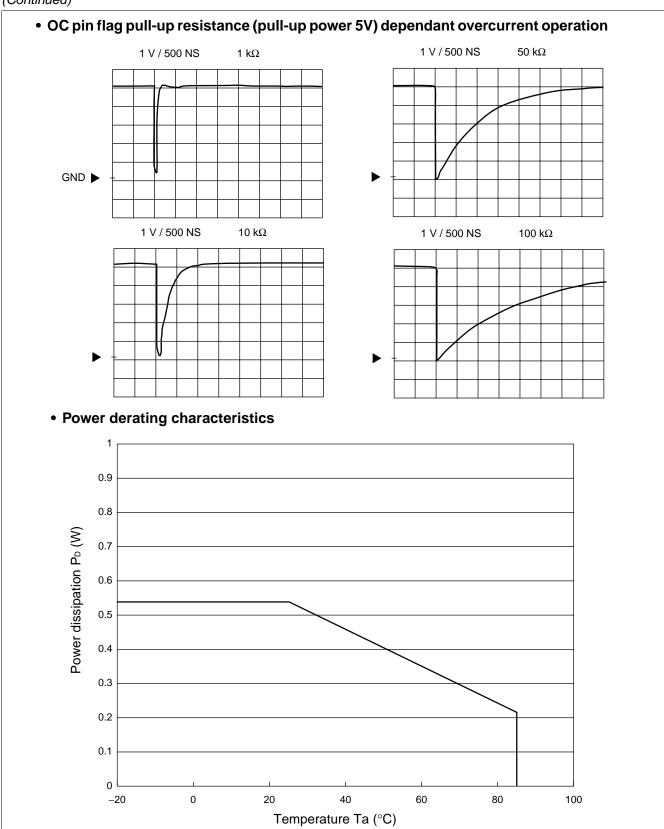


(Continued)



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■ FUNCTIONAL DESCRIPTION

Current Limit Setting

By placing resistance between the CS and GND pins, the current limit can be set between 100mA and 600mA within $\pm 30\%$ accuracy ($V_{IN}=5$ V, current limit at 600mA). Because the setting value is dependent on V_{IN} voltage, the user should select the optimum resistance value for the value of V_{IN} voltage. When the switching current exceeds the set value, the OC pin goes to "L" level as an external notification signal, but there is no latching function. To hold operation on "off" state, the input signal to the EN and $\overline{\text{EN}}$ pins should be used.

When a direct connection to GND is used, there is no current limitation.

When the connection is open, the switch is in a state of continuously held current limits.

Thermal Shutdown

The MB3842/MB3845 has a thermal shutdown function which turns the switch off and sets the latch to protect the device when junction temperature exceeds 125°C.

At the same time the OC output signal goes to "L" level to notify external systems.

The latch function can be reset by sending a low signal to the EN input of the MB3842, or a high signal to the EN input of the MB3845.

Slow Start

The on/off switching time can be delayed by applying capacitance between the SS and GND pins. Controlling the on time can soften surge current to the load side capacitance when power is turned on. For details, see "Css vs. ton (SS) characteristics" on p. 9.

UVLO

A V_{IN} voltage monitoring function is provided, so that when V_{IN} voltage exceeds 2.3 V (typ) the OC pin voltage goes to "H" level. When V_{IN} voltage falls below 2.1V (typ), the OC output goes to "L" state.

Error Flag OC Pin

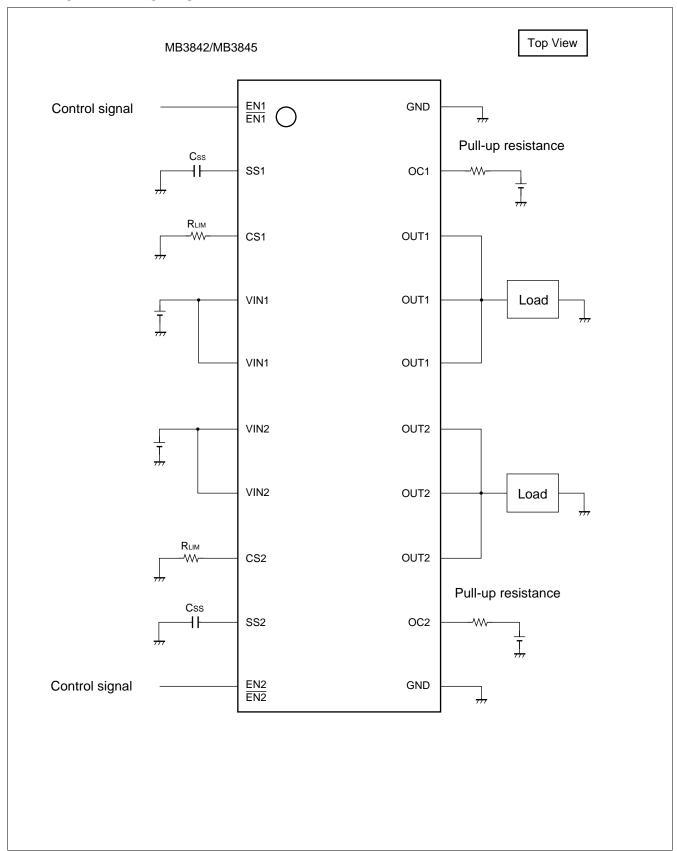
The OC pin produces a "L" signal in case of a UVLO, overcurrent, or over-temperature condition. In case of overcurrent, the output has a pulse waveform. See P12.

(note) Output current limit setting resistance values are shown on P9, and in the following table. (CS pin-to-GND)

Standard Values

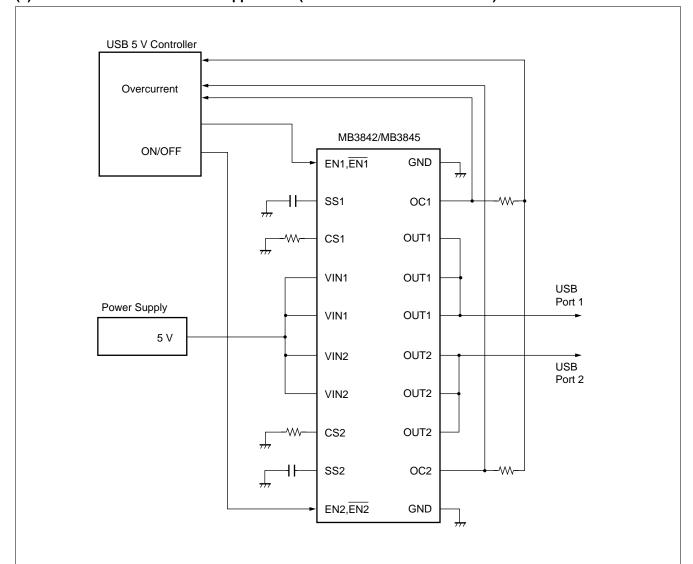
V _{IN} /Isw	0.1 A	0.2 A	0.3 A	0.4 A	0.5 A	0.6 A	0.7 A	0.8 A	0.9 A	1.0 A
Vin 5.0V	6.2 kΩ	4.3 kΩ	$3.3~\mathrm{k}\Omega$	2.7 kΩ	2.2 kΩ	2.0 kΩ	1.8 kΩ	1.6 kΩ	1.4 kΩ	1.3 kΩ
VIN 3.3V	9.1 kΩ	5.6 kΩ	4.3 kΩ	3.3 kΩ	2.7 kΩ	2.4 kΩ	2.0 kΩ	1.8 kΩ	1.6 kΩ	1.5 kΩ
Vin 2.5V	13 kΩ	7.5 kΩ	5.1 kΩ	3.9 kΩ	3.0 kΩ	2.7 kΩ	2.2 kΩ	2.0 kΩ	1.8 kΩ	1.6 kΩ

■ TYPICAL APPLICATION



■ APPLICATION EXAMPLE

(1) Dual-Port Self-Powered Hub Application (NON-GANG Mode Connection)

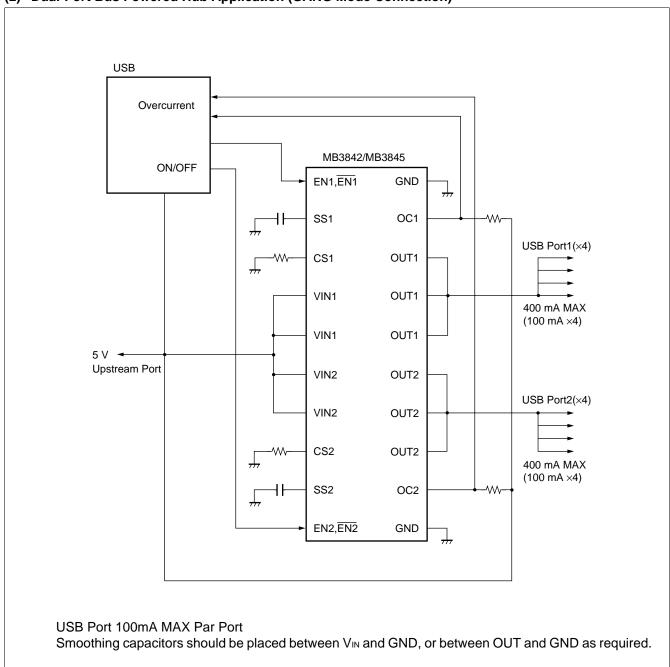


^{*}The MB3842 can also be adapted for use with 3.3V controllers.

USB Port 500mA MAX Par Port

Smoothing capacitors should be placed between VIN and GND, or between OUT and GND as required.

(2) Dual-Port Bus Powered Hub Application (GANG Mode Connection)



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■ USAGE PRECAUTION

1. Never use settings exceeding maximum rated conditions.

Exceeding maximum rated conditions may cause permanent damage to the LSI.

Also, it is recommended that recommended operating conditions be observed in normal use. Exceeding recommended operating conditions may adversely affect LSI reliability.

2. Use this device within recommended operating conditions.

Recommended operating conditions are values within which normal LSI operation is warranted.

Standard electrical characteristics are warranted within the range of recommended operating conditions and within the listed conditions for each parameter.

3. Printed circuit board ground lines should be set up with consideration for common impedance.

4. Take appropriate static electricity measures.

- Containers for semiconductor materials should have anti-static protection or be made of conductive material.
- After mounting, printed circuit boards should be stored and shipped in conductive bags or containers.
- Work platforms, tools, and instruments should be properly grounded.
- Working personnel should be grounded with resistance of 250 k Ω to 1 M Ω between body and ground.

5. Do not apply negative voltages.

The use of negative voltages below -0.3 V may create parasitic transistors on LSI lines, which can cause abnormal operation.

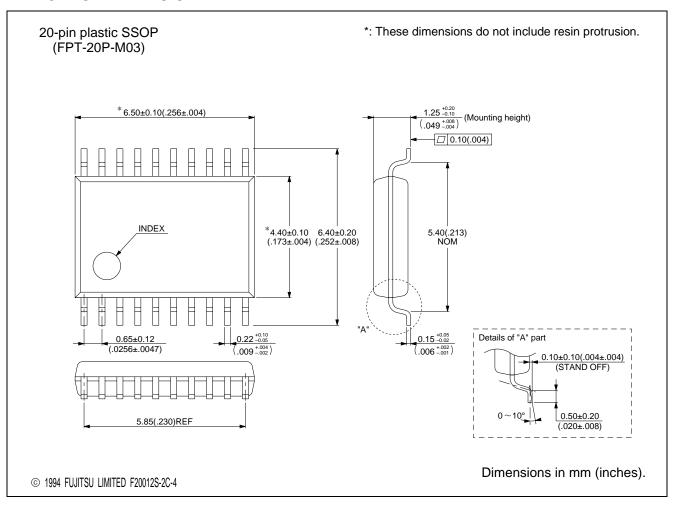
6. Reverse Current Prevention Function

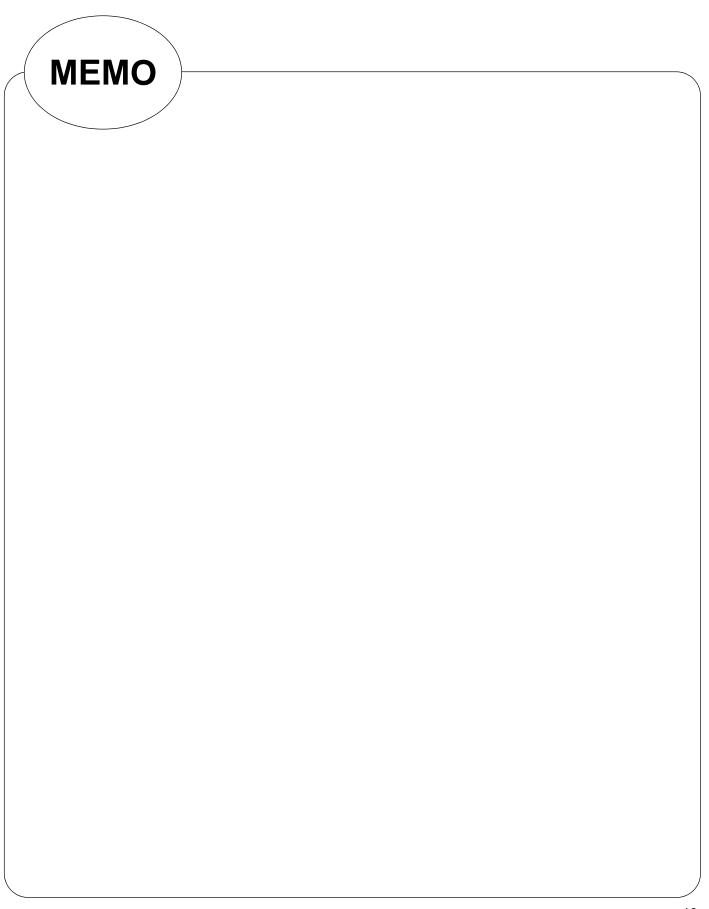
Current cannot flow back to the V_{IN} pin with the switch off, even when the OUT pin voltage is higher than the V_{IN} pin (OUT $\geq V_{IN}$), however when V_{IN} pin voltage is lower than 1.5 V circuit functions are lost, so that in this case there is danger of reverse current flow. For applications in which reverse flow is not acceptable, set $V_{IN} \geq 1.5 \text{ V}$.

■ ORDERING INFORMATION

Part number	Package	Remarks
MB3842PFV MB3845PFV MB3845PFV-ER	20-pin Plastic SSOP (FPT-20P-M03)	

■ PACKAGE DIMENSION





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